# **RECOMMENDED SOLDER PROFILES**

This document is intended as a reference for solder profiles for SEI resistive components. These profiles should be compatible with most soldering processes. These are only recommendations. Actual numbers will depend on board density, geometry, packages used, etc., especially those cells labeled with "\*".

### 100% Matte Tin/RoHS Compliant Terminations

Soldering iron recommended temperatures: 330°C to 350°C with minimum duration.

| Wave Soldering       |         |             |         |
|----------------------|---------|-------------|---------|
| Description          | Maximum | Recommended | Minimum |
| Preheat Time         | 80 sec. | 70 sec.     | 60 sec. |
| Temperature Diff.    | 140ºC   | 120ºC       | 100ºC   |
| Solder Temp.         | 260°C   | 250°C       | 240°C   |
| Dwell Time @ Max.    | 10 sec. | 5 sec.      | -       |
| Ramp DN (deg. C/sec) | NA      | NA          | NA      |

Temperature Diff. = Difference between final preheat stage and soldering stage.

| Convection / IR Reflow Soldering |          |             |         |
|----------------------------------|----------|-------------|---------|
| Description                      | Maximum  | Recommended | Minimum |
| Ramp Up (deg. C/sec)             | 3ºC/sec. | 2ºC/sec.    | -       |
| Dwell Time > 217°C               | 150 sec. | 90 sec.     | 60 sec. |
| Solder Temp.                     | 260°C    | 245°C       | -       |
| Dwell Time @ Max                 | 30 sec.  | 15 sec.     | 10 sec. |
| Ramp DN (deg. C/sec)             | 6ºC/sec. | 3ºC/sec.    | -       |

#### Recommended Lead Free Chip Resistor Reflow Profile



# www.bdtic.com/SEI

## **Sn-Pb Terminations**

Soldering iron recommended temperatures: 330°C to 350°C with minimum duration.

| Wave Soldering       |         |             |         |
|----------------------|---------|-------------|---------|
| Description          | Maximum | Recommended | Minimum |
| Preheat Time         | 80 sec. | 70 sec.     | 60 sec. |
| Temperature Diff.    | 140°C   | 120ºC       | 100ºC   |
| Solder Temp.         | 260°C   | 240°C       | 225°C   |
| Dwell Time @ Max.    | 4 sec.  | 3 sec.      | -       |
| Ramp DN (deg. C/sec) | NA      | 4ºC / sec.  | NA      |

Temperature Diff. = Difference between final preheat stage and soldering stage.

| Convection / IR Reflow Soldering |          |             |         |
|----------------------------------|----------|-------------|---------|
| Description                      | Maximum  | Recommended | Minimum |
| Ramp Up (deg. C/sec)             | 3ºC/sec. | 2ºC/sec.    | -       |
| Dwell Time > 180°C               | 150 sec. | 90 sec.     | 60 sec. |
| Solder Temp.                     | 260°C    | 225°C       | -       |
| Dwell Time @ Max                 | 20 sec.  | 15 sec.     | 10 sec. |
| Ramp DN (deg. C/sec)             | 4ºC/sec. | 2ºC/sec.    | -       |

| Vapor Phase Soldering |          |             |         |
|-----------------------|----------|-------------|---------|
| Description           | Maximum  | Recommended | Minimum |
| Ramp Up (deg. C/sec)  | 4ºC/sec. | 2ºC/sec.    | -       |
| Dwell Time > 183°C    | 85 sec.  | 75 sec.     | -       |
| Solder Temp.          | 220°C    | 215°C       | -       |
| Dwell Time @ Max      | 75 sec.  | 70 sec.     | -       |
| Ramp DN (deg. C/sec)  | 4ºC/sec. | 2ºC/sec.    | -       |

For further information, please contact Kory Schroeder, Director of Marketing, at <u>kschroeder@seielect.com</u> or 919-875-2495.